

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	TLE8104E	**Issued**	9. January 2019
MA#	MA004091384		
Package	PG-DSO-20-71	**Weight***	598.01 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	10.435	1.74	1.74	17449	17449
leadframe	inorganic material	phosphorus	7723-14-0	0.051	0.01		85	
	non noble metal	zinc	7440-66-6	0.203	0.03		339	
	non noble metal	iron	7439-89-6	4.058	0.68		6785	
	non noble metal	copper	7440-50-8	164.755	27.55	28.27	275508	282717
wire	non noble metal	copper	7440-50-8	1.509	0.25	0.25	2523	2523
encapsulation	organic material	carbon black	1333-86-4	0.817	0.14		1366	
	plastics	epoxy resin	-	37.589	6.29		62857	
	inorganic material	silicondioxide	60676-86-0	370.171	61.90	68.33	619010	683233
leadfinish	non noble metal	tin	7440-31-5	4.487	0.75	0.75	7503	7503
plating	noble metal	silver	7440-22-4	0.767	0.13	0.13	1283	1283
glue	plastics	epoxy resin	-	0.791	0.13		1323	
	noble metal	silver	7440-22-4	2.373	0.40	0.53	3969	5292
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com